

BFQ18A NPN 4 GHz wideband transistor Rev. 03 – 28 September 2007

Product data sheet

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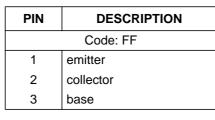


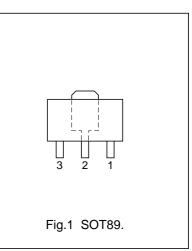
BFQ18A

NPN 4 GHz wideband transistor

DESCRIPTION

NPN transistor in a plastic SOT89 envelope intended for application in thick and thin-film circuits. It is primarily intended for MATV purposes.





QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS		MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	25	V
V _{CEO}	collector-emitter voltage	open base	-	18	V
I _C	DC collector current		_	150	mA
P _{tot}	total power dissipation up to $T_s = 155 \text{ °C}$ (note 1)		_	1	W
f _T	transition frequency	I_{C} = 100 mA; V_{CE} = 10 V; f = 500 MHz; T _j = 25 °C	4	-	GHz
C _{re}	feedback capacitance	I _C = 0; V _{CE} = 10 V; f = 10.7 MHz	1.2	-	pF
d _{im}	intermodulation distortion	$\begin{split} I_{C} &= 80 \text{ mA}; \text{ V}_{CE} = 10 \text{ V}; \text{ R}_{L} = 75 \Omega; \\ V_{o} &= 700 \text{ mV}; \text{ measured at} \\ f_{(p+q-r)} &= 793.25 \text{ MHz} \end{split}$	_	-60	dB

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER CONDITIONS		MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	25	V
V _{CEO}	collector-emitter voltage	open base	_	18	V
V _{EBO}	emitter-base voltage	open collector	-	2	V
I _C	DC collector current		-	150	mA
P _{tot}	total power dissipation	up to $T_s = 155 \text{ °C}$ (note 1)	-	1	W
T _{stg}	storage temperature		-65	150	°C
Tj	junction temperature		-	175	°C

Note

1. T_s is the temperature at the soldering point of the collector tab.

THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
	thermal resistance from junction to soldering point	up to $T_s = 155 \ ^\circ C$ (note 1)	20 K/W

Note

1. T_s is the temperature at the soldering point of the collector tab.

CHARACTERISTICS

 $T_j = 25 \ ^{\circ}C$ unless otherwise specified.

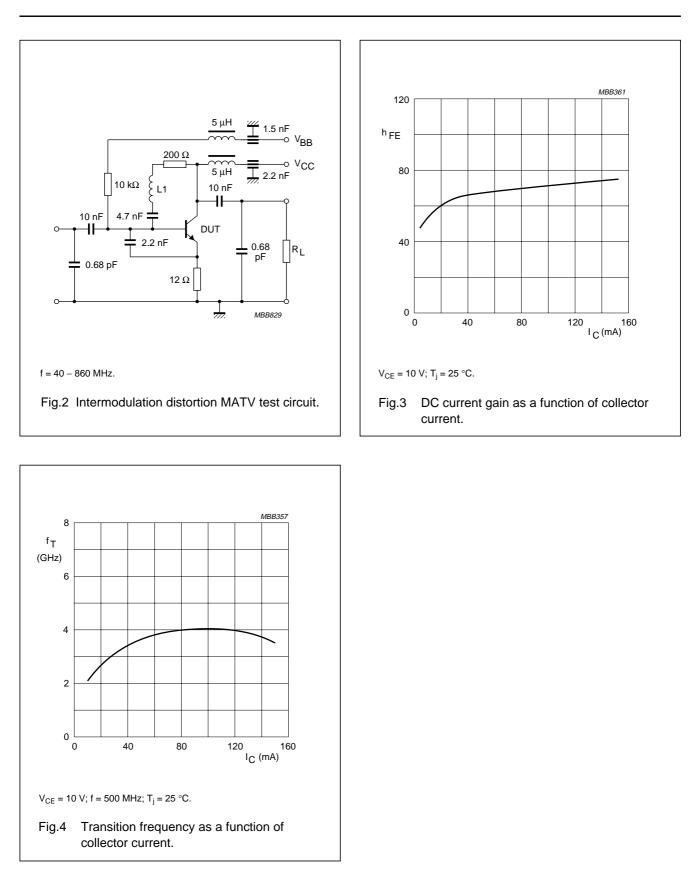
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	UNIT
h _{FE}	DC current gain	I _C = 100 mA; V _{CE} = 10 V	25	-	
Cc	collector capacitance	$I_E = i_e = 0; V_{CB} = 10 V; f = 1 MHz$	-	2	pF
C _e	emitter capacitance	$I_{C} = i_{c} = 0; V_{EB} = 0.5 V; f = 1 MHz$	-	11	pF
C _{re}	feedback capacitance	I _C = 0; V _{CE} = 10 V; f = 10.7 MHz	-	1.2	pF
f _T	transition frequency	I _C = 100 mA; V _{CE} = 10 V; f = 500 MHz	-	4	GHz
d _{im}	intermodulation distortion (see Fig.2)	note 1	-	-60	dB

Note

 $\begin{array}{ll} 1. & I_c = 80 \text{ mA}; \ V_{CE} = 10 \ V; \ R_L = 75 \ \Omega; \\ V_p = V_o = 700 \ \text{mV}; \ f_p = 795.25 \ \text{MHz}; \\ V_q = V_o - 6 \ \text{dB}; \ f_q = 803.25 \ \text{MHz}; \\ V_r = V_o - 6 \ \text{dB}; \ f_r = 805.25 \ \text{MHz}; \\ \text{measured at } f_{(p+q-r)} = 793.25 \ \text{MHz}. \end{array}$

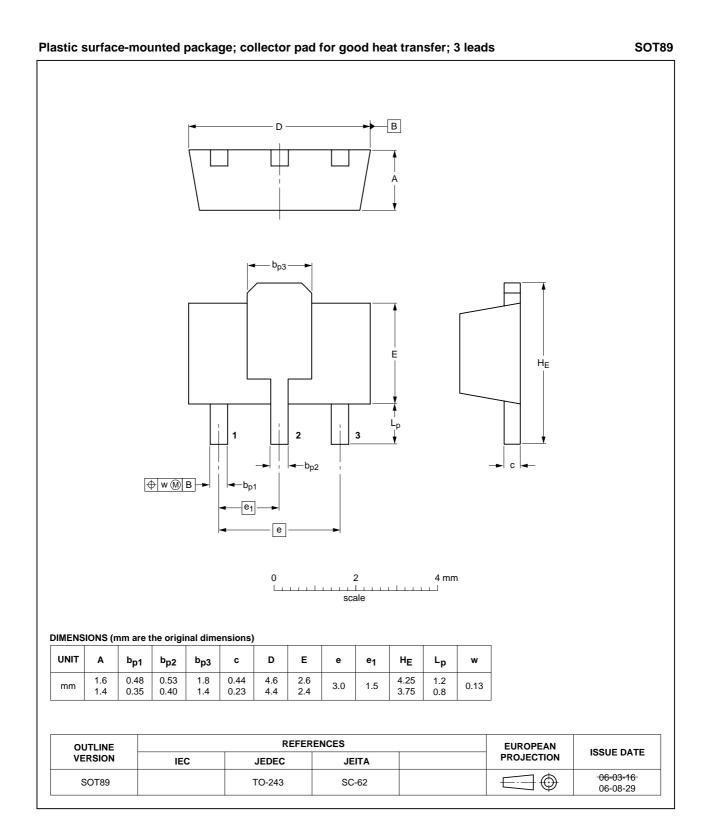
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PACKAGE OUTLINE



Legal information

Data sheet status

Document status[1][2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Revision history

Revision history							
Document ID	Release date	Data sheet status	Change notice	Supersedes			
BFQ18A_N_3	20070928	Product data sheet	-	BFQ18A_CNV_2			
Modifications:	 Fig. 1 and p 	ackage outline updated					
BFQ18A_CNV_2	19950901	Product specification	-	-			

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